

substrate in the form of aluminum nitride plate with thickness of 6.0 mm. The resulting ceramic substrate was trimmed on both side by 1 mm to flatten the surface at the level of flatness of 3 μm . The trimmed ceramic substrate was cut to a disk of diameter of 210 mm, then the opposite side of the wafer heating surface was polished to provide recesses of depth 1 millimeter. Power supply terminals were attached to the through holes exposed in the recesses, and connected to a casing.

Page 40, line 15 - line 16:

(4) Some passing-through holes 64 were drilled (see Fig. 11B).

Page 44, line 19 - page 45, line 8

A ceramic heater according to the present invention has at least part of heat generation means disposed within a ceramic substrate, offset to a level different from that of others of the heat generation means in the direction of thickness of the ceramic substrate. The offset formation of at least part of heat generation means to a level different from that of others of the heat generation means may cause the expansion or shrinkage of heat generation bodies to be occurred at levels different each other. Therefore the ceramic heater in accordance with the present invention may disperse thermal shocks to entire ceramic substrate to reduce the effect thereof, and may achieve better anti thermal shock property. In addition, the ceramic heater in accordance with the present invention does not decrease uniformity of heating characteristics on the wafer-heating surface.

REMARKS

The attached Appendix includes marked-up copies of each rewritten paragraph (37 C.F.R. §1.121(b)(1)(iii)) and claim (37 C.F.R. §1.121(c)(1)(ii)).

In view of the foregoing amendments and remarks, Applicant submits that this application is in condition for allowance. Favorable reconsideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number set forth below.

Respectfully submitted,



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Attachment:
Appendix

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